

Serial No. 10/759,706

IN THE CLAIMS

Claim 1 (currently amended): ~~A housing~~ An assembly for enclosing an electronic element of an electronic device, comprising:

a housing enclosing the electronic element;

a first hole in the housing for injecting a substance therinto;

a second hole ~~for evacuating air~~ in the housing;

a substance of nonconductive, non-corrosive, and high heat capability and which is injectable into the first hole of the housing while air is evacuated from the second hole of the housing to completely fill the housing with the substance; and

two stop members inserted ~~in~~ into the holes for sealing the housing after the substance completely fills the housing injection so that the electronic element is adapted to be waterproof and vibration-proof, and has a predetermined heat dissipation capability, wherein the housing is formed of plastic material without electromagnetic waves shielding capability.

Claim 2 (canceled).

Claim 3 (currently amended): The ~~housing assembly~~ of claim [[2]] 1, wherein the plastic material is rubber.

Claim 4 (currently amended): The ~~housing assembly~~ of claim 1, wherein the substance is a fluid of nonconductive, non-corrosive, and high heat transfer capability.

Claim 5 (currently amended): The ~~housing assembly~~ of claim 4, wherein the fluid is silicon oil.

Claim 6 (currently amended): The ~~housing assembly~~ of claim 4, wherein the fluid is hydro oil.

Claim 7 (currently amended): The ~~housing assembly~~ of claim 1, wherein the substance is semisolid.